ASSOCIATION CONNECTING ELECTROMICS INDUSTRIES INDUSTRIES International and Pan-A]. Bannockb	urn. Illinois. A	ll rights reserved un tions.	nder both	This docum level parts, t	ent is a declarati he declaration e	on of the sub ncompasses a	stances w all lower	vithin the manufacture level materials for wh	er listed i hich the r	tem. Note: if nanufacturer	the item is an as has engineering	sembly with lower responsibility.
	IPC Web Site for Information on IPC-1752 Standard Form Ty http://www.ipc.org/IPC-175x Distribution				* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Material				als and M	ls and Mfg Information			
Supplier Information													
Company name* Comp			ompany unique ID			Unique ID Authority				Response Date*			
nsemi									2024-05-11				
Contact Name	ne Title - Contact				Phone - Contact*				Email - Contact*				
roduct-Env-Stewards Product Enviro			ro Compliance			NA			Product-Env-Stewards@onsemi.com				
Authorized Representative* Title - Represent			sentative		Phone - Representative*			Email - Representative*					
Product-Env-Stewards Product			oduct Enviro Compliance			NA				Product-Env-Stewards@onsemi.com			
Requester Item Number	Mfr Item Number		ber Mfr Item Name			Effective Date	Version	М	Manufacturing Site		Weight*	UOM	Unit Type
	AMIS427	MIS42770ICAW1G HS CAN REP		TER		2024-05-11		Pł	PHG		612.57	mg	Each
Manufacturing Proccess Information	on		-					ŀ				·	·
Terminal Plating / Grid Array Mate	Array Material Terminal Base Alloy		Alloy J	-STD-020 MSL Rating		Peak Process Body Temperature Ma		e Max Time at Peak	eak Temperature Number of Reflow Cycles		les		
Matte Tin (Sn) - annealed CU Alloy		2	2		260	0	2	30	secor	nds 3			
Comments													
ATTENTION: MSL 2 Rated item requires l	Dry Pack (a	fter electrical	test)										
For more information regarding material co	mposition j	please refer to	page 3										

RoHS Material Composition Declaration				Declaration Type *	Detailed							
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).											
cadmium, hexavalentchromium, polybrominate contains a RoHS restricted substance inexcess encompass all such components. Supplier certif as of the date that Supplier completes this form Company acknowledges that Supplier may hav independently verified information provided by certification in this paragraph. If the Company a	ed biphenyls and/or polybrominated dip of an applicable quantity limit, please ir ies that it gathered the information it pro- .Supplier acknowledges that Company e relied on informationprovided by othe v others, Supplier agrees that, at a minin and the Supplier enter into a written agre pource of the Supplier's liability and the	henyl ethers (each a " ndicate below which, i ovides in this form us will rely on this certifiers in completing this num, itssuppliers have eement with respect to Company's remedies	RoHS restricted substance") in exce if any, RoHS exemption you believe ing appropriate methods to ensure if ication in determining the complian form, and that Supplier may not have e provided certifications regarding the to the identified part, the terms and cc for issues that arise regarding inform	ce of its products with European Union membe	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the anty rights and/or remedies provided as part of							
RoHS Declaration * 1 - Item(s)	does not contain RoHS restricted substa	on above	Supplier Acceptance	* Accepted								
Exemption: If the declared item does not con applicable exemptions.	ntain RoHS restricted substances per	the definition above	except for defined RoHS exempti	ons, then select the corresponding response i	n the RoHS Declaration above and choose all							
Exemption List Version	EL-2011/534/EU											
Declaration Signature												
Instructions: Complete all of the required fin Requester) and click on Submit Form to have	elds on all pages of this form. Select the form returned to the Requester	he "Accepted" on th	e Supplier Acceptance drop-down	. This will display the signature area. Digital	lly sign the declaration (if required by the							
Supplier Digital Signature Ra	stislav Drska	Le										

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3

sigma range of distribution unless otherwise noted).									
Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure	
Die	35.93	mg	Supplier	Silicon (Si)	7440-21-3		35.93	mg	
Die Attach	6.55	mg	Supplier	Epoxized Condensate Of Para- Hydrobenzaldehyde And Alkyl Phenol	129915-35-1		1.5065	mg	
			Supplier	Silver (Ag)	7440-22-4		5.0435	mg	
Lead Frame	188.57	mg	Supplier	Zinc (Zn)	7440-66-6		0.1886	mg	
			Supplier	Iron (Fe)	7439-89-6		4.3371	mg	
			Supplier	Copper (Cu)	7440-50-8		183.8558	mg	
			Supplier	Phosphorus (P)	7723-14-0		0.1886	mg	
Mold Compound-Black	377.0	mg		Epoxy Phenol Resin	proprietary data		39.585	mg	
			Supplier	Fused Silica (SiO2)	60676-86-0		337.415	mg	
Plating	3.7	mg	Supplier	Tin (Sn)	7440-31-5		3.7	mg	
Wire Bond - Au	0.82	mg	Supplier	Gold (Au)	7440-57-5		0.82	mg	